REMARKS

This paper is responsive to any paper(s) indicated above, and is responsive in any other manner indicated below.

PENDING CLAIMS

Claims 15-27 were pending, under consideration and subjected to examination in the Office Action. Appropriate claims have been amended in order to adjust a clarity and/or focus of Applicant's claimed invention. That is, such changes are unrelated to any prior art or scope adjustment and are simply informality amendments. At entry of this paper, Claims 15-27 remain pending for further consideration and examination in the application.

REJECTION UNDER '112, 2ND PAR. OBVIATED VIA CLAIM AMENDMENT

Claims 17-18 have been rejected under 35 USC '112, second paragraph, as being indefinite for the concerns listed within the section numbered "2" on page 2 of the Office Action. Claims 17-18 have been carefully reviewed and carefully amended where appropriate in order to address the Office Action listed concerns. As the foregoing is believed to have addressed all '112 second paragraph concerns, reconsideration and withdrawal of the '112 second paragraph rejection are respectfully requested.

REJECTION UNDER 35 USC '103

The 35 USC '103 rejection of claims 15-27 is respectfully traversed. In support of such traversal, all descriptions of Applicant's disclosed and claimed invention, and all descriptions and rebuttal arguments regarding the applied prior art, as previously submitted by Applicant in any form, are repeated and incorporated hereat by reference. Further, all Office Action statements regarding the prior art rejections are respectfully traversed. As additional arguments, Applicant respectfully submits the following remarks from Applicant's foreign representative in support of traversal of the rejection and patentability of Applicant's claims.

The present invention relates to a resin mold package having a lead frame formed by the press method.

(1) The feature of claims 15 and 27 is "In case of using the chip mounting portion of a smaller size than that of the chip, the chip is mounted on the surface side at which burrs of lead frame is not formed". As shown in the attached SKETCH (A), since flatness of the surface of chip mounting portion is secured, the reliance of fixing strength between the chip and the chip mounting portion can be reliably increased, and also the location stability of the chip in the sealing resin can be improved.

On the other hand, as shown in the attached SKETCH (B), if the chip is mounted on the other surface side at which burrs of lead frame is formed", the flatness of the surface of chip mounting portion is degraded, so the above-effect can not be obtained.

(2) The second feature of claim 15 is " In case of using a wire bonding technique, the wire bonding is performed at the surface side of the plurality of leads at which burrs of lead frame is formed". As shown in the attached SKETCH (C), since the wire bonding capable area of the surface of leads relatively becomes wider, the adhesion reliance between the leads and bonding wires can be increased.

On the other hand, as shown in the attached SKETCH (D), if the wire bonding is performed at the other surface side of the plurality of leads at which burrs of the lead frame are not formed, the wire bonding capable area of the surface of leads effectively becomes narrower, so the adhesion reliance between the leads and bonding wires is degraded.

As to the cited references, none of the applied references discloses the above-features(1) and/or (2) as defined in the present claims. More particularly, Frechette et al. (U5P4,868,635) merely discloses that a portion of inner leads of the lead frame is cut in accordance with the chip size.

Mitsubishi(JP64-39740) discloses the technique that "at the time of molding process, clamping pressure for clamping the lead frame(2) is strengthened as shown in Fig.3 to deform the projections of lead frame(2) at the vicinity of tie bar parts and to prevent the resin burrs from flowing-out to the out of molding dies(1)". More particularly, Mitsubishi is concerned with a reduction of the occurrence of burs. Accordingly, the purpose of Mitsubishi(JP64-39740) is clearly different from our claimed invention, and is far from the features of our claimed invention. That is, Applicant's invention embraces proper orientation of the burs to improve mounting and lead soldering, whereas Mitsubishi is trying to reduce/eliminate burs.

As a result of all of the foregoing, it is respectfully submitted that the applied art (taken alone and in the Office Action combinations) would not support a '103 obviousness-type rejection of Applicant's claims. Accordingly, reconsideration and withdrawal of such '103 rejection, and express written allowance of all of the '103 rejected claims, are respectfully requested. Further, at this point, it is respectfully submitted as a reminder that, if new art is now cited against any of Applicant's unamended claims, then it would not be proper to make a next action final.

35 USC 251, RECAPTURE REJECTION - TRAVERSED

The 35 USC 251 recapture rejection of claims 15-27 is respectfully traversed. More particularly, MPEP 1412.01 allows a reissue Applicant to claim an invention which was disclosed within Applicant's original disclosure, even if it was not claimed in the original patent. In the present reissue, Applicant is now claiming the original FIGS. 3 and 11(b) embodiment involving proper placement/orientation of "burs" (see item 11 in Applicant's FIG. 3), as validly allowed by MPEP 1412.01. While the alleged recapture "[s]uspension leads unitarily ....by adhesive" limitations may have been important to ones of Applicant's prior '913 patent claims directed to a differing invention, such limitations are irrelevant to, and thus are in included in, Applicant's present differing "bur" invention/claims. Further, Applicant's "bur" limitations are narrowing limitations in the sense that "bur" limitations were not included within Applicant's prior '913 claims. MPEP 1412.02 states (in relevant part) "If the narrowing limitation modifies the claim in such a manner that the scope of the claim

no longer results in a recapture of the surrendered subject matter, then there is no recapture." Such is the case here, i.e., the present focus is on the "bur" invention.

EXAMINER INVITED TO TELEPHONE

The Examiner is herein invited to telephone the undersigned attorneys at the local Washington, D.C. area telephone number of 703-312-6600 for discussing any Examiner's Amendments or other suggested actions for accelerating prosecution and moving the present application to allowance.

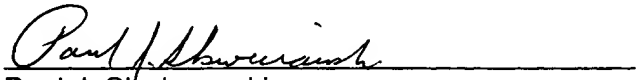
CONCLUSION

In view of the foregoing amendments and remarks, Applicant respectfully submits that the claims listed above as presently being under consideration in this divisional reissue application are now in condition for allowance. Accordingly, early allowance of such claims is respectfully requested.

To the extent necessary, Applicant petitions for an extension of time under 37 CFR '1.136. Please charge any shortage in fees necessitated by this Preliminary Amendment or divisional reissue application, including excess claim fees, to ATS&K

Deposit Account No. 01-2135 (as Order No. 501.32049RV1), and credit any overpayment or excess fee thereto.

Respectfully submitted,



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ATTACHMENTS:

Sketch A-D drawing sheet

SKETCH for explanation of the claimed invention